

**METHODS OF FORMING METALLURGY STRUCTURES FOR  
WIRE AND SOLDER BONDING AND RELATED STRUCTURES**

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**ABSTRACT**

Metallurgy structures for input/output pads of an electronic devices can  
be adapted to receive both solder and wire bonds. First and second  
metallurgy structures, for example, can be provided on respective first and  
10 second input/output pads of an electronic device such that the first and  
second common metallurgy structures have a shared structure adapted to  
receive both solder and wire bonds. A solder bond can thus be applied to the  
first metallurgy structure, and a wire bond can be applied to the second  
metallurgy structure.

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